

Product Summary

| $V_{(BR)DSS}$ | $R_{DS(on)TYP}$ | I_D |
|---------------|-----------------|-------|
| 60V | 1.1Ω@10V | 340mA |
| | 1.4Ω@4.5V | |

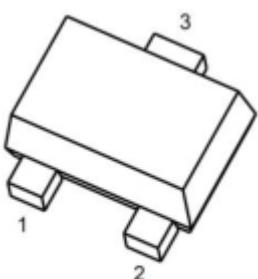
Feature

- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- Capable doing Cu wire bonding
- ESD protected Gate HBM 2KV

Application

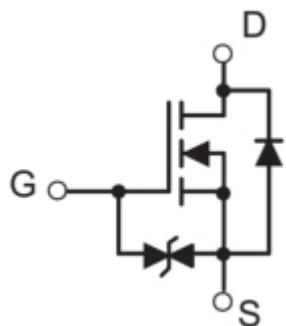
- Power Management in Note book
- Portable Equipment
- Battery Powered System

Package

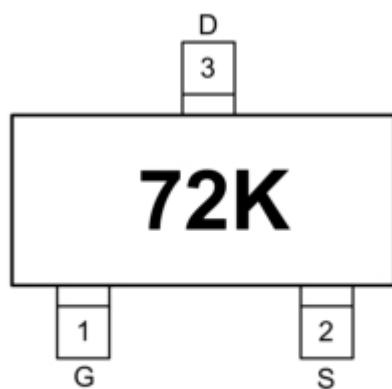


SOT-723

Circuit diagram



Marking



72K =Device Code

Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|---|-----------------|----------|---------------------------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current | I_D | 340 | mA |
| Power Dissipation | P_D | 0.15 | W |
| Thermal Resistance from Junction to Ambient | $R_{\theta JA}$ | 833 | $^\circ\text{C}/\text{W}$ |
| Junction Temperature | T_J | 150 | $^\circ\text{C}$ |
| Storage Temperature | T_{STG} | -55~+150 | $^\circ\text{C}$ |



ZL MOSFET

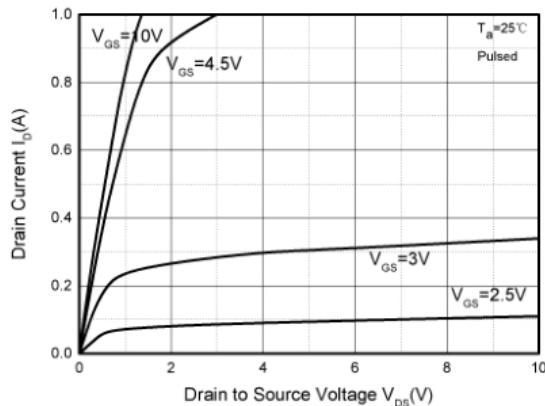
2N7002KT7

Electrical characteristics

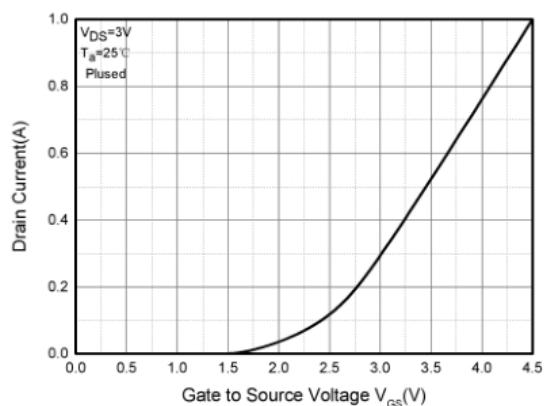
(T_A=25°C, unless otherwise noted)

| Parameter | Symbol | Test Condition | Min. | Typ. | Max. | Unit |
|---|----------------------|---|------|------------|--------|------|
| Static Characteristics | | | | | | |
| Drain-source breakdown voltage | V _{(BR)DSS} | V _{GS} = 0V, I _D = 250μA | 60 | | | V |
| Gate threshold voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250μA | 1 | 1.5 | 2.5 | V |
| Gate-body leakage current | I _{GSS} | V _{DS} = 0V, V _{GS} = ±20V | | | ±10 | uA |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 60V, V _{GS} = 0V | | | 1 | uA |
| Drain-source on-resistance | R _{DS(on)} | V _{GS} = 10V, I _D = 200mA V _{GS} = 4.5V, I _D = 200mA | | 1.1 1.4 | 3 4 | Ω |
| Dynamic characteristics | | | | | | |
| Total Gate Charge | Q _g | V _{DS} =10V, V _{GS} =4.5V, I _D =250mA | | 0.3 | | nC |
| Gate-Source Charge | Q _{gs} | | | 0.2 | | |
| Gate-Drain Charge | Q _{gd} | | | 0.08 | | |
| Input Capacitance | C _{iss} | V _{DS} =25V, V _{GS} =0V, f=1MHz | | 30 | 50 | pF |
| Output Capacitance | C _{oss} | | | 4.2 | 25 | |
| Reverse Transfer Capacitance | C _{rss} | | | 2.9 | 5 | |
| Switching Characteristics | | | | | | |
| Turn-On Delay Time | t _{d(on)} | V _{DD} =30V, I _D =200mA, V _{GEN} =10V, R _G = 25Ω | | 3.9 | | ns |
| Turn-On Rise Time | t _R | | | 3.4 | | |
| Turn-Off Delay Time | t _{d(off)} | | | 15.7 | | |
| Turn-Off Fall Time | t _F | | | 9.9 | | |
| Source-Drain Diode Characteristics | | | | | | |
| Diode Forward voltage | V _{SD} | V _{GS} = 0V, I _S =200mA | | 0.82 | 1.3 | V |

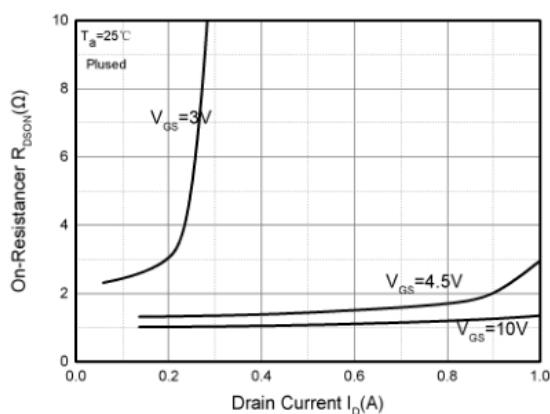
Typical Characteristics



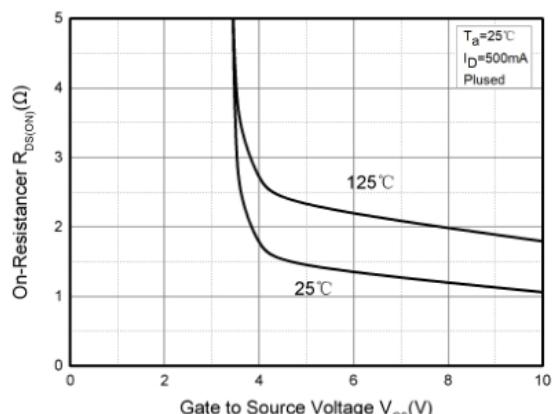
Output Characteristics



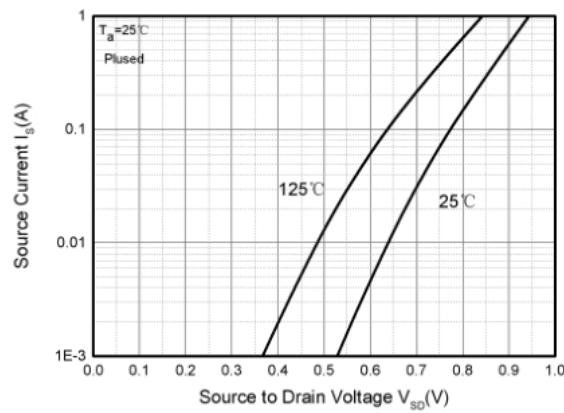
Transfer Characteristics



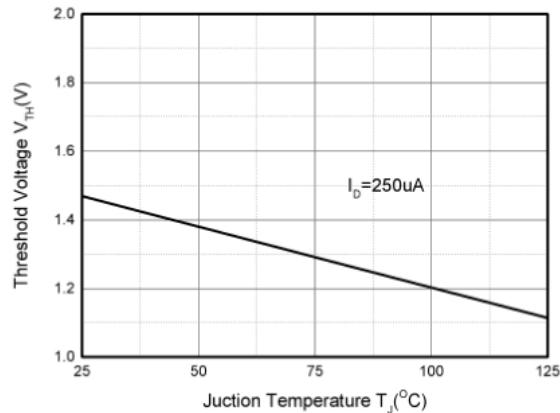
On-Resistance vs. Drain current



On-Resistance vs. Gate to Source Voltage

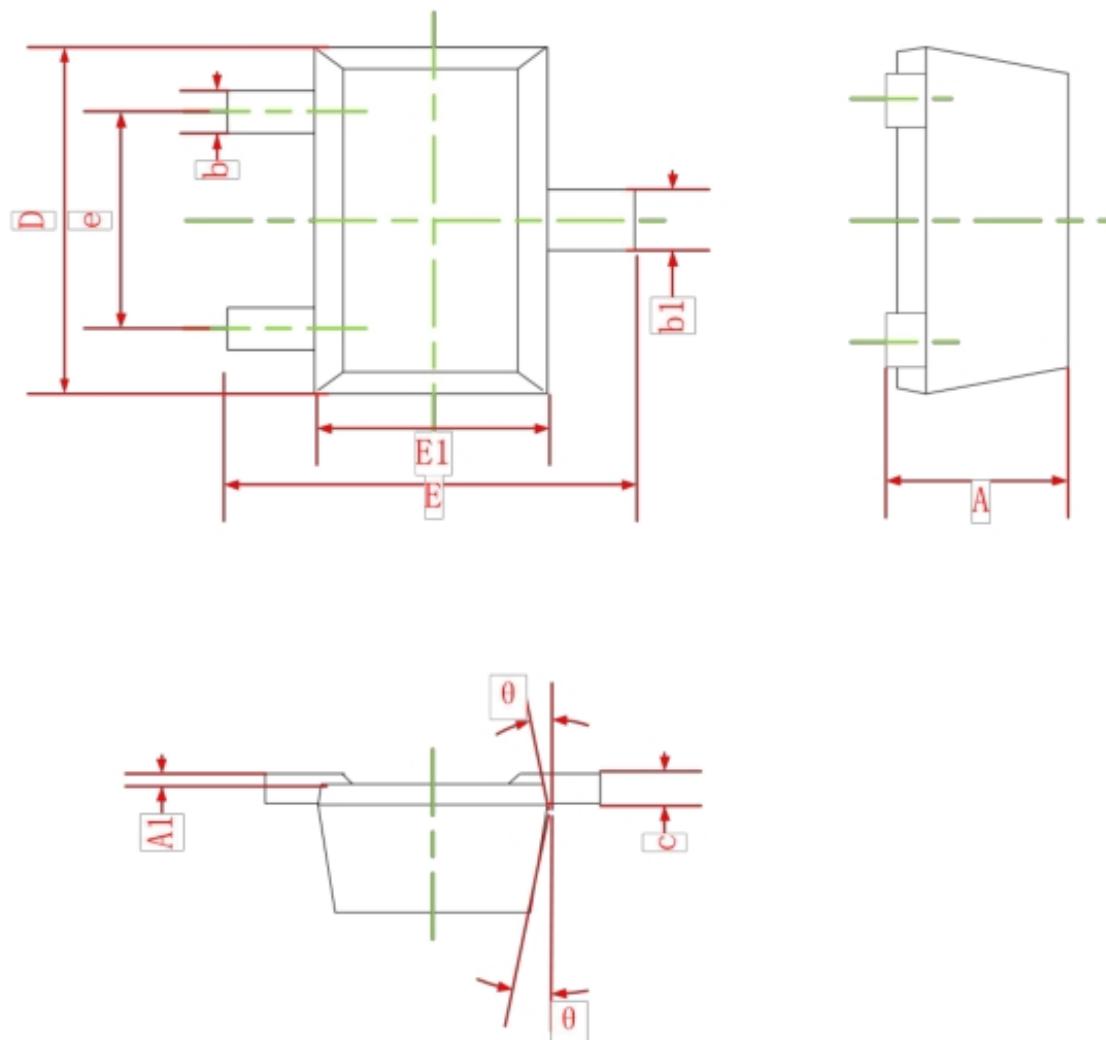


Source Current vs. Source to Drain Voltage



Threshold voltage vs. Junction temperature

SOT-723 Package Information



| Symbol | Dimensions In Millimeters | |
|--------|---------------------------|-------|
| | Min. | Max. |
| A | 0.430 | 0.500 |
| A1 | 0.000 | 0.050 |
| b | 0.170 | 0.270 |
| b1 | 0.270 | 0.370 |
| c | 0.080 | 0.150 |
| D | 1.150 | 1.250 |
| E | 1.150 | 1.250 |
| E1 | 0.750 | 0.850 |
| e | 0.800TYP. | |
| θ | 7° REF. | |